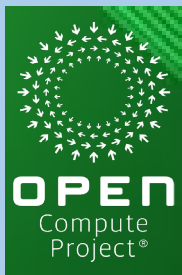




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Chiplet Design Considerations FPGA use case

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Today's slides share considerations for chiplet developers

Chiplet Market is booming seems like a great idea to develop one and be early to **market for open chiplets.**

Barriers –

IP needed?

Die to Die standards – which one?

KGD - Redundancy?

KYC – know your chiplet?

Validation platform?

Marketplace?



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● IP Needed

- First what process ?
- Next Foundry target ?
- Packaging – standard, advanced?
- Die2Die PHY ? Bump Map? Bump pitch ?
- Link Layer ?
- Speed ?
- Power ?
- Clocking – PLL - 2Ghz?
- **NO CENTRAL INFO RESOURCE**

● Die2Die standards

- BOW and UClc
- BOW is more bare metal – more flexible
- Next Gen BOW 2.0 is around the corner
- UClc is more fixed and less flexible
- Consider supporting both – if you want to increase TAM chiplet on open market

● KGD – known good die

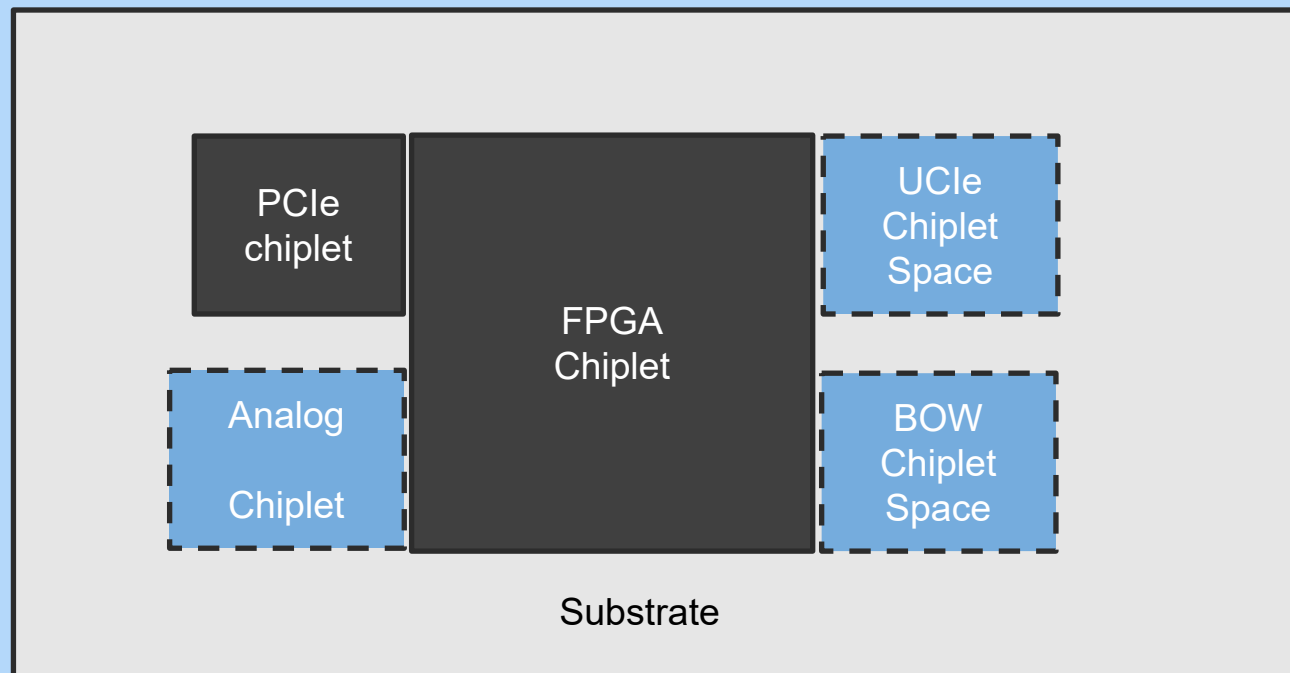
- Chipelets economics work great when all the chipelets work
- As no rework - economics become a disaster if one fails
- Little **secret ESD is being dramatically reduced for D2D**
- We are working with a partner to run system level test on complete chipelet via Die2Die interface. Make sure chipelet is working fully in package. Can run @ power up & self test.
- **Build in Redundancy into chipelet design** – failure is not an option. Small chipelets especially critical. Not just at die2die interface. Advanced packaging more difficult to test.

●KYC – know your chiplets

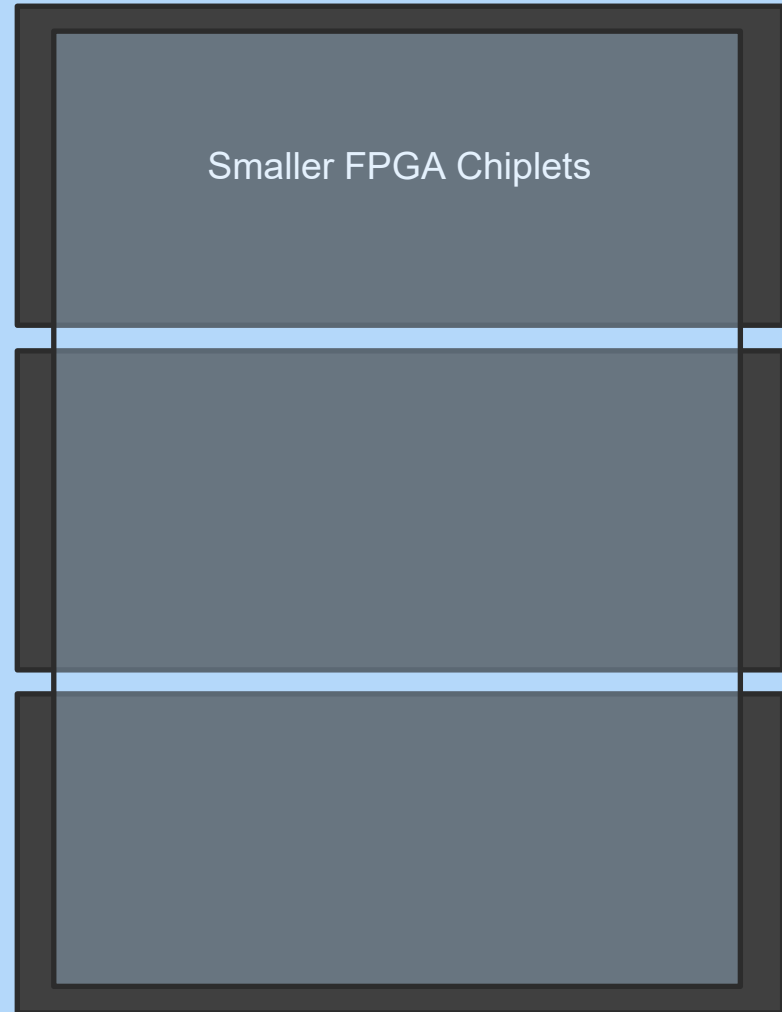
- As chiplets will be stored in die form
- Supply chain is important but not infallible
- Root of Trust security will be important
- We are working with a partner to secure our chiplets with unique identifier - technology is already out there
- Do consider root of trust or it or could limit your market

● Validation of your chiplet?

- Currently **no easy validation system exists**
- We hope to have one by mid 2024
- Third party chiplets, ASICs, I/O chiplets



● Choices



Redundant Architecture
Any 2 of 3 must work
Program can be loaded depending on failure
Failure not an option

● Open Marketplace?

- Ooops there is no OPEN chiplet market yet
- **Coming soon** Hopefully



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